REMARKS/ARGUMENTS

Claims 13-35 have been withdrawn from consideration. Claims 1-12 and 36-38 are pending. Claims 1-4, 9-12 and 36-38 have been rejected over Starinshak et al. Claims 5-8 have been rejected over Starinshak in view of Andricacos et al.

In the present amendment, claims 1 and 5 are being amended and claim 2 is being canceled. Reconsideration is requested.

Referring to amended claim 1, the plating liquid container is able to contain the plating liquid in a greater amount than the plurality of plating vessels. No such plating system is disclosed in any of the cited references.

Referring to amended claim 5, Andricacos et al. (U.S. Patent No. 5,352,350) cannot disclose or suggest the claimed replacement liquid supplying section. This reference only discloses "replacing" an old plating liquid bath with a new plating liquid bath. As a result of the present amendment, the replacement liquid recited in claim 5 separates the copper supply source from the plating liquid, and therefore cannot be a plating liquid bath. Hence, the invention of amended claim 5 is distinguishable from the invention of the cited references.

As for claim 9, Starinshak et al. do not disclose a weight measuring section and a control section specifying how to select the copper dissolution tank. Therefore, the invention of claim 9 is not obvious to one of ordinary skill in the art, even if the prior art discloses a pair of copper dissolution tanks.

As for claims 36-38, Starinshak et al. do indeed recite that "the copper anode can be of any geometric shape" and suggests a few specific shapes that may be used. However, Starinshak et al. do not disclose the shapes of the copper supply sources recited in claims 36-38 of the

present application. Nothing in the reference suggests what is actually claimed. There is no suggestion or motivation in the art to modify the teachings of Starinshak to thereby invent the subject matter of claims 36-38. The general language in Starinshak et al. is no substitute for prior art disclosing a copper anode having the features actually claimed.

In particular, Starinshak et al. do not disclose that any copper supply source is oriented "parallel to the flow path," as recited in claims 37 and 38 of the present application). This fact also distinguishes claim 7, reciting that the mesh members (the copper supply source) are stacked one on another along a flow path of the plating liquid in the dissolution tank.

In view of the foregoing amendments and remarks, allowance of claims 1, 3-12 and 36-38 is requested.

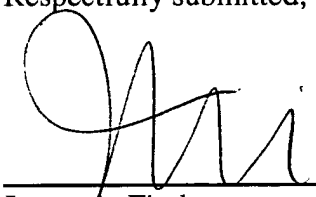
I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on February 9, 2006:

James A. Finder
Name of applicant, assignee or Registered Representative

Signature

February 9, 2006
Date of Signature

Respectfully submitted,



James A. Finder
Registration No.: 30,173
OSTROLENK, FABER, GERB & SOFFEN, LLP
1180 Avenue of the Americas
New York, New York 10036-8403
Telephone: (212) 382-0700

JAF:lf